出國報告

晶片系統國家代表團 中加 SoC 國際雙邊會議及參訪行程

Canada-Taiwan System-On-Chip Session Delegation (July 17th - 26th, 2004)

- 出團背景
- 團員名單
- 出團行程
- 會議紀要
- 参訪紀要
- 追蹤事項
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- 附錄
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 - 照片選輯
 - 雙方簡報檔案(另檔呈送)

■ 出團背景

緣起:

由於我國在半導體製程之晶圓代工產業技術居世界龍頭地位,加國在晶片電路設計之實力業已成為世界矚目之星,因此我國與加國在晶片系統的開發上是硬體與軟體的合作與相輔相成。

國科會多年來積極推動我國與加國之合作關係,因此加國友善地邀請參加 IEEE International SoC Workshop 並共同負責年會中之兩國 SoC 之雙邊會議,往後由雙方每年輪流當地主國舉辦此會議,互派產官學研各界代表共聚一堂以切磋研發心得,並尋找雙方可能之實質合作商機,達到雙贏之目標,共為促進兩國 SoC 產業而努力。

雙方合作籌辦單位:

加拿大駐台經貿辦事處

加拿大工業局

加拿大微機電協會組織(Canadian Microelectronics Corporation-CMC)

卡加力大學(University of Calgary)

亞伯塔大學(University of Alberta)

ATI Technologies, Toronto

Snowbush Microelectronics, Toronto

Diablo Technologies, Ottawa

Pultronics, Montreal

SiWorks, Calgary

MoSys Canada, Ottawa

PDF Solutions, San Jose

行政院國科會

工研院系統晶片中心(STC, ITRI)

台灣 SoC 推動聯盟(Taiwan SOC Consortium)

晶片系統國家型科技計畫辦公室(NSoC Program Office)

國家實驗研究院國家晶片系統設計中心(CIC)

雙邊會議規劃委員:

- Dr. Wael Badawy, Professor, University of Calgary, Calgary, Canada
- Dr. Yarsun Hsu, Professor, National Tsing Hua University, Taiwan
- Dr. Kris Iniewski, Professor, University of Alberta, Edmonton, Canada
- Mr. Keith Parsonage, Director General, Industry Canada, Ottawa, Canada
- Mr. Peter Stokes, Senior Manager, Canadian Microelectronics Corporation (CMC), Kingston
- Mrs. Marie-Louise Hannan, Deputy Director, Canadian Trade Office Taipei (CTOT)
- Dr. Jing-Yang Jou, Director of National Chip Implementation Center, Professor, Department of Electrical Engineering, NCTU

■ 團員名單

* G for Government, A for Academy, R for Research Institute, I for Industry

			lemy, R for Research		
No.	*	Name	Title	Institution	Remarks
1	Α	黄威	講座教授	Dept. of E.E, National Chiao-Tung Univ.	Head of
	,	Dr. Wei Hwang	Chair Professor	Dopti of 2.2, Hational office Fairy of the	Delegation
		Dr. Wei riwang	Director	Microelectronics and Information	Dologation
			Director	Systems Research Center	
2	٨	木為一	ガナバ		
2	А	李鎭宜	系主任	交通大學電子系	
		Dr. Chen-Yi Lee	Chairman	Dept. of Electronics Engineering, NCTU	
3	Α	蘇朝琴	教授	Dept. of Electronic and Control	
		Dr. Chau-Chin Su	Professor	Engineering, NCTU	
			Executive Director;	晶片系統國家型科技計畫辦公室	
				National System-on-Chip (NSoC)	
				Program Office;	
4	Α	溫瓌岸	教授	交通大學	
		Dr. Kuei-Ann Wen	Professor	Dept. of Electrical Engineering, NCTU	
5	Λ	陳良基	所長	台灣大學	
3	^				
		Dr. Liang-Gee Chen	Director	Graduate Institute of Electronics,	
				National Taiwan University (NTU)	
6	Α	許雅三	教授	清華大學	
		Dr. Yarsun Hsu	Professor	Dept. of Electrical Engi.	
				National Tsing Hua University(NTHU)	
7	G	周景揚	主任	國家晶片系統設計中心	
		Dr. Jing-Yang Jou	Director	National Chip Implementation Center	
Ω	Δ	張克正	Associate	清華大學	IEEE SOCRT
0	^	–			
		Dr. Keh-Jeng Chang	Professor	Dept. of Computer Science, National	發表論文
	_			Tsing Hua University	
9	А	馬振茹	業務組長	晶片系統國家型科技計畫辦公室	
		Ms. Cheng-Ju Ma	NSoC Officer	National System-on-Chip (NSoC)	
				Program Office	
10	I	楊丁元	主席	台灣SoC推動聯盟	產業界代表
		Dr. Ding-Yuan Yang	Chairman	Taiwan SoC Consortium	
		g	董事長	源捷科技	
			至于八	FameG Sota	
11		#:士#.	經理		
11				智原科技	
		黄克勤		Laraday Jachnology Heinchii Jaiwan	
		Mr. Hwung Keh-Chien	Marketing Manager	·	
12	I		Marketing Manager 副部長	聯電	
12	I	Mr. Hwung Keh-Chien		·	
12	I	Mr. Hwung Keh-Chien 莫亞楠	副部長	聯電	
12	I	Mr. Hwung Keh-Chien 莫亞楠	副部長 Deputy Division Director of Design	聯電	
		Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou	副部長 Deputy Division Director of Design Support Division	聯電 UMC	
13		Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰	副部長 Deputy Division Director of Design Support Division 處長	聯電 UMC 台積電	
		Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou	副部長 Deputy Division Director of Design Support Division 處長 Director of Design	聯電 UMC	
13	I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services	聯電 UMC 台積電 TSMC	
	I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang 張榮輝	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services	聯電 UMC 台積電 TSMC	
13	I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services	聯電 UMC 台積電 TSMC	
13	I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張爾彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael Rong Whei	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services 總工程師 Chief Architect	聯電 UMC 台積電 TSMC 旺玖科技 Prolific Technology Inc.	
13	I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael Rong Whei 林寶樹	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services 總工程師 Chief Architect	聯電 UMC 台積電 TSMC 旺玖科技 Prolific Technology Inc. 工研院電通所	
13	I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張爾彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael Rong Whei	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services 總工程師 Chief Architect	聯電 UMC 台積電 TSMC 旺玖科技 Prolific Technology Inc. 工研院電通所 Computer and Communications	
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13	I I	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael Rong Whei 林寶樹 Dr. Bao-shuh Paul Lin	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services 總工程師 Chief Architect 所長 General Director	聯電 UMC 台積電 TSMC 旺玖科技 Prolific Technology Inc. 工研院電通所 Computer and Communications Research Laboratories, Industrial Technology Research Institute (CCL/ITRI)	
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13 14 15	I R	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael Rong Whei 林寶樹 Dr. Bao-shuh Paul Lin 周露華 Ms. Amy Chou	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services 總工程師 Chief Architect 所長 General Director 專案經理 Project Manager of International Program Center	聯電 UMC 台積電 TSMC 旺玖科技 Prolific Technology Inc. 工研院電通所 Computer and Communications Research Laboratories, Industrial Technology Research Institute (CCL/ITRI) 工研院國際合作室 Industrial Technology Research Institute (ITRI)	
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13 14 15	I R	Mr. Hwung Keh-Chien 莫亞楠 Mr. Yanan Mou 張彌彰 Dr. Mi-Chang Chang 張榮輝 Mr. Chang, Michael Rong Whei 林寶樹 Dr. Bao-shuh Paul Lin 周露華 Ms. Amy Chou	副部長 Deputy Division Director of Design Support Division 處長 Director of Design Services 總工程師 Chief Architect 所長 General Director 專案經理 Project Manager of International Program Center 組長	聯電 UMC 台積電 TSMC 旺玖科技 Prolific Technology Inc. 工研院電通所 Computer and Communications Research Laboratories, Industrial Technology Research Institute (CCL/ITRI) 工研院國際合作室 Industrial Technology Research Institute (ITRI) 工研院系統晶片中心	

18	R	謝秀卿	經理	工研院系統晶片中心/台灣SoC推動聯盟	
		Ms. Vivien Hsieh	Business Officer	STC/ITRI and Taiwan SoC Consortium	
19	R	簡讚慶	顧問	工研院系統晶片中心	7/23加入
		Mr. Jzan-Ching Jeen	Consultant	STC/ITRI	
20	R	王揚文	前維新科技副董	碩英企業唯新科技	7/23加入
		Yang-Wen Wang	Private Investor	Smartek	
				Tecnology Corp/SegaTek Corp.	

■出團行程

PROGRAMME

Data 0 Time			Damarila
Date & Time	Event	Location	Remarks
July 17 (Saturday)	Flight Cahadula DD40 TDF W/D 2255/4040	1/000000000	1
	Flight Schedule:BR10 TPE-YVR 2355/1940 Arrival & check-in	Vancouver	
July 18(Sunday)	Allival & Check-III		
July To(Juliuay)	Flight Schedule:WS210 YVR-YYC 0900/1120	VancouverBanff	
		varicouverDariii	
July 19(Monday)			
08:30am-12.30pm	Canadian Workshop For System-on-Chip	Banff Conference	Contact
00.00diii 12.00piii	(CWSOC 2004)	Centre, Banff	person:
	Preliminary Program	, , , , ,	Hugh W.
	, ,		Pollitt-Smith
08:30am	Opening Remarks, SOCRN Overview		pollitt-smith@c
	(Peter Stokes, CMC)		ma.ca
08:45am	SOCRN Upcoming Infrastructure (CMC)		
09:30am	UBC SOC Laboratory		
	(Dr. Resve Saleh, UBC)		
09:50am	Rapid-Prototyping SoC for Multimedia Applications		
	(Dr. Wael Badawy, University of Calgary)		
40:40===	The Charlin Multipus assess Dietferm		
10:10am	The StepNP Multiprocessor Platform		
10.200	(Charles Pilkington, STMicroelectronics)		
10:30am 10:50am	Coffee Break		
10.50am	SOC Verification: State-of-the-art and Proposed Solutions(Dr. Sofiène Tahar, Concordia University)		
	Solutions(Dr. Soliene Tahai, Concordia Oniversity)		
11:10am	Open Discussion		
12:00pm	- Lunch		
13:00pm-19:00pm	Canada-Taiwan System-On-Chip Session	Banff Conference	Contact
	Januara raman System on omposion	Centre, Banff	person:
			Dr. Yarsun Hsu
			yshsu@ee.nth
			u.edu.tw
13:00pm-14:40pm			
	Achieving Competitive Advantage through		
	International Research Collaboration		
	Session Chair and introductory remarks: Dr.		
	Brian Burge, President and CEO, Canadian		
	Microelectronics Corporation(CMC)		
	Walaamin u manaanka Ma Kaith Danaa a		
	Welcoming remarks: Mr. Keith Parsonage,		
	Director General, Information Technologies		
	Industry Branch, Industry Canada		
	Mr. Peter A. Stokes, Senior Manager, CMC,		
	"The Transition in Canada from SoCs to		

	一	TIK U	
14:40pm-15:00pm 15:00pm-16:00pm	Microsystems" ■ Dr. Wei Hwang, Chair Professor, Dept. of E.E, NCTU "The National Si-Soft Initiative - Taiwan's Second High-Tech Revolution" ■ Mr. Terry Ludlow, Chipworks, "Presentation TBA" ■ Dr. Ding-Yuan Yang, Chairman, Taiwan SoC Consortium, " Cooperation in the SOC Era" Coffee Break Invited Talks (2) Leveraging SOC Research to Succeed in a Competitive Global Market Session Chair and introductory remarks: Dr. Chau-Chin Su, Professor of the Dept. of Electronical and Control Engineering, NCTU		
	 Dr. Ramesh Senthinathan, Director, ATI Technologies, Toronto: "High-Speed Clock and Data Recovery Design for Consumer, Network, Communications and Storage" Dr. Bao-Shuh Paul Lin, General Director, CCL, ITRI, "SoC/IP Development for ICT and Digital Video Applications at CCL/ITRI" Dr. Ken Martin, President and Co-Founder, Snowbush Microelectronics, Toronto: "The Fastest Path to Production Starts with a Multi-Project Prototype; Optimum Design Methodologies and Examples of Analog and Mixed-Mode Cores" 		
16:00pm-16:15pm	Coffee Break		
16:15pm-18:30pm	Short Presentation and Discussion		
	 The Challenge: Taking SoC Research to Market Chair: Peter Stokes, Senior Manager Engineering Operations, CMC Format: Individuals made ten-minute presentations that identify research interests and possible collaboration topics. Participants: Mr. Riccardo Badalone, CTO, Diablo Technologies, Ottawa Dr. Liang-Gee Chen, Director, Institute of Electronics, National Taiwan University, "Opportunities and Challenges of StarIP Development" Mr. Sreedhar Natarajan, Director, MoSys Canada, Ottawa Dr. Chen-Yi Lee, Chairman, Dept. of Electronics Engineering, NCTU, "IP Promotion: The way to Valu-Added SoC" Dr. Kuei-Ann Wen, Professor, Department of Electrical Engineering, NCTU "Design for wireless SoC" Dr. Kris Iniewski, Professor, University of 		
	 Alberta, Edmonton, Canada Mr. Mark Gonzales, Technical Advisor, PMC-Sierra Mr. Huang Keh-Ching, Marketing Manager, Earaday Technology, Heinebu, Taiwan 		
	 Mr. Mark Gonzales, Technical Advisor, PMC-Sierra 		

	 Dr. Mi-Chang Chang, Director of Design Services, TSMC, Mr. Chang, Michael Rong Whei, Chief Architect of Prolific Technology Inc. "Media streaming SOC development and application" Mr. Yanan Mou, Deputy Division Director of Design Support Division " Challenges of RFSOC from foundry point of view" 	
19:30pm- 21:30pm	Networking Dinner The session concluded with a social event that provided ample opportunities to make business contacts leading to industry-to-industry and industry-university collaborations.	
July 20(Tuesday	y)	

	Pusings Opportunities Session	•	
08:30am-16:25pm	Business Opportunities Session	The Banff Center, Banff	
08:30am-08:35am	Opening Introduction & Welcome (Event Chair)		
	David Antoniuk – Director,		
	Electronics/Microelectronics and Nanotechnolgy –		
08: 35am-08:40am	Alberta Innovation & Science Introduction & Welcome		
00. 33am-00.40am	Dr. Wei Hwang - Chair Professor and Director -		
	Department of Electronics Engineering		
	/Microelectronics & Information Systems Research		
	Centre		
	Dr. Ding-Yuan Yang, Chairman of Taiwan SoC		
08:45am-09:05am	Consortium Introduction & Welcome / Presentation on		
00.43am-09.03am	Canada's ICT Sector		
	Keith Parsonage - Director General, Industry		
	Canada-ICT Branch		
09:10am-09:30am	Presentation – Scanimetrics		
00:250	Steve Slupsky - CEO		
09:35am-09:55am	Presentation – FameG Sota Dr. Ding-Yuan Yang, Chairman		
10:00am-10:20am	Presentation – SiWorks		
	Mr. Mike Lee, Director		
10:25am-10:40am	Networking Break		
10.10	Drogontotion Cilicomative Colletions		
10:40am-11:00am	Presentation – Silicomotive Solutions Mr. Jerzy Swic - Senior Principal Engineer		
11:05am-11:25am	Presentation – Prolific Technology Inc.		
	Mr. Chang Zon-Huei, Manager		
11:30am-11:50am	Presentation – Non Elephant Encryption (NE2)		
10.00	Brian Mackie, President		
12:00pm-13:30pm	Lunch - Keynote speakers		
	Dr. MA, GIN-KOU: Overview of the SOC Technology Center (STC)		
	Amy Chou: Opportunities and Advantages of		
	establishing an innovative R&D Centre in Taiwan		
13:35pm-13:55pm	Presentation – Faraday		
44.00	Mr. Huang Keh–Ching, Marketing Manager		
14:00pm-14:20pm	Presentation – Diablo Technologies Mr. Riccardo Badalone, Chief Technical Officer		
14:25pm-14:45pm	Presentation – UMC		
zopiii 17.7opiii	Mr. Yanan Mou, Deputy Division Director		
14:50pm-15:00pm	End of Event -Prepare Room for Individual		
	Company Meetings		
15:00pm 16:05===	one-on-one Discussion		
15:00pm-16:25pm	one-on-one Discussion		
	IEEE International Workshop on SoC for		
	Real-Time Applications (for Academia)		
	Keynote Speech:		
	Title: SoC Integration Challenges Speaker: Russell Klein, Mentor Graphics		
	Opeaner. Russell Rielli, Melliul Graphius		
July 21(Wednesda	y)		
08:30am-	Individual Visit (for Industry) or	Calgary	
17:00pm	IEEE International Manhabara COCC		
'	IEEE International Workshop on SoC for Real-Time Applications (for Academia)		
	Todi-Time Applications (for Academia)		
July 22(Thursday)			
09:00am-	Visit TRLabs in Calgary	Calgary-	

12:00pm	Suite 280, 3553 - 31 Street NW, Calgary T: 403.289.3140, F: 403.282.5870	Vancouver			
July 23(Friday)					
09:00am-	Visit PMC-Sierra in Vancouver	Vancouver			
10:30am	PMC Sierra Office Operations Headquarters 105 - 8555 Baxter Place, Burnaby				
July 24(Saturday)					
	Back to VancouverIndividual Visit to CompaniesMeeting with other companies for special topic	Vancouver			
July 25(Sunday)					
	Flight Schedule:BR09 YVR-TPE 0220/0510+1	VancouverTaipei			
July 26(Monday)	Arrival in Taipei				

● 會議紀要

July 18 pm-- Meeting of NsoC & Canada-Alberta

Attendee:

Taiwan: Wei Hwang, Chau-chin Su, Jing-Yang Jou, Cheng-Yi Lee

Canada: David Antoniuk, Dan Djukich, Graham Jullien, Dave Murphy, Wael Badawy

Summary:

- Two sides both agreed to
 - 1. Sign Letter of Intent
 - 2. Identify suitable research group
 - 3. Setup a research meeting in Taiwan/Canada to define the research topics and the format of cooperation (6 months)
 - 4. Apply for research funding in each own country. Ministry of Innovation and Sceince of Alberta and NsoC of Taiwan will help in allocating and obtain funding on each sides.
 - 5. Detail cooperation format discussed in 2005 IWSoC (July 2005).
 - 6. Sign MOU 2005 Fall in Taiwan.
- SoC is a common interest, the cooperation can be
 - 1. Research Exchange
 - 2. IP
 - 3. MEMS
 - 4. System Technology
- NSC-NRC research cooperation MOU is more on Nanotechnology related topic. Prof.
 Lee need to information NSC to raise microelectronic issue to NSC official in next week
 NSC-NRC meeting.
- Antoniuk: Taiwan-Canada can cooperate in MEMS area with Alberta's strong design

capability of MEMS (Micralyne) and strong manufacturing capability of Taiwan.

July 19 a.m. -- Canadian Workshop For System-on-Chip (CWSOC 2004)

上午場為加方國內產學研共同舉辦的 CSWOC 2004 workshop, 由 Canadian Microelectronics Corporation (CMC) 介紹 The System-On-Chip Research Network (SOCRN)。 SOCRN 擁有來自加拿大 30 所大學的研發團隊,致力於 Advanced computer-aided design tools, intellectual property blocks (system-on-chip components), and methodologies。其他學界如 UBC、 Calgary 大學及 Concordia 大學亦分別介紹其目前 SoC 實驗室現況與 SoC 相關技術之發展。

July 19 p.m. -- Canada-Taiwan System-On-Chip Session

此部份方正式進入由台灣與加方兩國為 SoC 產業透過雙邊技術研發討論以共同取得國際競爭優勢之「中加 SoC 雙邊會議」。參加者超過 70 人,short presentation and discussion 部分,並引發雙邊產學研界熱烈討論,先摘要加方簡報如下: (對方未提供電子檔)

- ATI short talk on "high speed clock and data recovery design for consumer, network communication and storage" by Dr. Ramesh Senthinathan
 - 6Hhz Serdes project of his former starup company
 - six sigma design
 - Horizontal : jitter
 - Vertical : ISI , Xtalk,
 - MDLL 1.73ps rms,
 - Pre-emphasis and equalization to be used to resolve ISI problem
- 2. CMC (Canadian micro-electronic co.)
 - Company to coordinate university projects of national fund.
 - SOC use micro-system to interpretate the SOC concept
 - Focus on MEMS, micro fluid, optical, electronics, bio
- 3. Chipwork company introduction
 - Main business: knowledge provider thru. Reverse engineering
 - Reverse engineering can help to gain competitive advantage
 - Learning from others recognized by paten office
 - Encouragement of patent filing knowledge sharing
 - In return, patent protection for 20 years of monopoly
 - Intel always be the 2nd for new technology adoption
 - SOI
 - Copper

- Strained silicon
- Low K
- 4. Snowbush microelectronics Ken martin (IEEE fellow, former professor of UCLA and co-founder of broadcom)
 - Leading provider of Analog IC design service and related IP
 - OSC.
 - AD/DA
 - DVI TX
 - SerDes
 - Give tech and ckt away unique business model
 - Think analog synthesis not feasible
 - Would like to develop further close relationship with UMC

綜合結論:

加方代表熱烈討論台灣成功模式,與加方相對於政府策略、優惠措施、學界計劃等之比較。我方亦回應台灣半導體環境初始有政府高層的全力支持是一關鍵,及後整體產業鏈上中下游完整的發展,再加上世界級的 foundry 廠,成為 SoC 產業最大的 support 與助力。不過,從對方簡報中習得,加方學研不惜成本、不以賺錢為目的的致力於基礎研發與創新研發,其技術紮根甚深,尤其是 analog 方面的設計, 皆是台灣最需學習的關鍵。他們弱在成本太高,及 foundry 與 process 之不足,而我方以營利為目的,所研發出來的產品技術相對的較無創新之價值。此為我方與加方在排除競爭利益之外,應可互補之技術合作之處。此會議相信已在中加兩方之參加者中,留下雙方技術能力及合作意願之印象與媒合機會,並期盼所引出一些未來可能之合作項目供雙方參加者評估與後續之回應。

July 20 -- Business Opportunities Session

此會議純以中加雙方產業界為主體,為媒合兩國 business units 之技術合作機會目的而召開之商談會。共有台灣 5 家廠商、加方 5 家廠商提供公司簡報。現場參加者約有50 位,會後並有 one-on-one 之對談,對談表如下:

15:00-1 5:25	UMC meeting with	Faraday meeting with	TSMC meeting with	Prolific meeting with	FameG Sota meeting with
	Diablo(2)	NE2 (4)	Scanimetrics (1)	SilicoMotive	NE2 (3)
	UMC meeting with	Faraday meeting with	TSMC meeting with	Prolific meeting with	FameG Sota meeting with
	Scanimetrics(2)	Diablo	NE2(1)	NE2	SilicoMotive
	UMC meeting with	Faraday meeting with	TSMC meeting with	Prolific meeting with	FameG Sota meeting with
	NE2(2)	SilicoMotive	Diablo		

加方之公司簡報摘記如下:

- 1. Scanimetrics Contact less testing solution provider
 - Contact-less testing
 - RF probe card, power can be induced or use separate power
 - Glass + silicon to form the probe card
 - RF cell build into the DUT in the free space
 - \$200K for the price of probe card
 - To seek co-op opportunity with UMC.
 - Introduce to TPES (paul Chen) and follow up with tele-conf...
- 2. SiWork IP company (focus on MAC)
 - Wireless IP
 - Uwb, 80211, ...
 - Wirelined IP
 - Giga

3.Silicomotive

- IP company
- Digital IP in telecommunication area
- Mux, dmux, sonnet, access area

4.NE2

- IP company
- Both software and hardware approach
- Cryptosystem, cryptographic IP
- Symmetry vs. asymmetry encryption
 - Symmetry: single key fast but less security
 - Asymmetry: public / private key slow, AES, RSA
- To offer AES with no key exchange
- Show Interest to join UMC gold IP program

綜合結論:

此部份提供兩國廠商一個導引合作的開端,會後是否會有繼續的交流與合作,仍需一段時間,才能了解是否能成為真正技術合作的商業夥伴。感謝 TSMC 與 UMC 的參與,吸引對 foundry 需求甚高之加方廠商之參與。加方 IP 公司也希望參考 Faraday, FameG Sota 等 design service 模式,期跳脫競爭對手思維,尋找出共同的合作模式。從此會議中,台灣產學研也開始重新思考,國內廠商應能團結,找出自身專精的 market 與 research 境域, 相互區隔與相互相輔相成,團結進入國際市場,方能於國際 SoC

技術市場上佔有關鍵之席地。

■ 参訪紀要

TRLabs 訪問摘要:

TRLab (17 years of history) - R&D Lab in Canada

- platinum membership- 400k. plus 260k (indirect contribution)
- 5 labs 260 People. 50% students
- 54 members (Samsung, Nortel..). Focus on comm.(optical. Wireless)
- non exclusive free royalty model to members who access its technology
- 240/800 projects transfer to industry.
- ROI 30%
- Nano technology (quantum dot) majority gate instead of logic gate design approach (quantum dot)
- Would like to invite twain industry to join their membership

TRLabs 的經營模式頗為特殊,其以類似聯盟模式,招收會員,收取會費。 research team 中,也涵蓋學生,且會員間,技術移轉不再收取royalty 費用,此種模式,已整合產學研資源,可為台灣借鏡。

PMC-Sierra訪問摘要:

- Foundry mainly in TSMC
- focus on communication and Consumer
- 940 people. 16 locations
- 3 product lines : micro-processor. Telecomm., . storage network
- 0.2%UI at 3.125 ghz serdes
- TSMC low k info. (0.13um)3.6, (90nm)2.9, (65nm)2.4
- 90nm 2004. 65nm 2006
- Internal 600 digital IP. 200 analog IP
- External IP needed in the future
 - RF
 - ✓ Bluetooth
 - ✓ 802.11
 - ✓ GSM/CDMA
 - Analog
 - ✓ Audio ADC/DAC
 - √ Video ADC/DAC

■ 追蹤事項

此次會議後,兩國對口聯繫單位皆讚許此雙邊交流效益,已初步確認明年將再回邀加方產官學研至台灣延續舉辦此雙邊會議,時間預定於明年 IEEE VLSI-TSA 會議(Apr. 27-29) 前後,地點待定。

雙方聯絡窗口:

加方為 Dr. Wael Badawy/University of Calgary

台灣為 Dr. Yarsun Hsu, National Tsing Hua University

■總結

此次 NSoC 辦公室黃威主任能主導此中加 SoC 雙邊會議,聚集學界台大、交大、清大與國家晶片系統設計中心,及研發界工研院 CCL 與 STC 等之 SoC 技術教授與專家等之齊聚一堂之參與。並由台灣 SoC 聯盟邀請業界: foundry 廠台積電、聯電,Design Service 智原與源捷,IC Design 旺玖科技等共襄盛舉。不僅造就此團產官學研團員間內部溝通與整合意見之機會,並結合力量共同為台灣赴加拿大打了一場高科技外交的漂亮戰役。

會議之後,引發國內需積極思考如何整合 SoC 產業整合運作之議題,應加速進行。台灣目前在全球半導體產業完整產業鏈之利基下,如何快速於 SoC 技術發展趨勢脫穎而出,須靠產官學研,各領域的專業分工,整合資源,尋找共通運作模式,方可於國際舞台共同領先商機與攻佔主導地位。

NSoC 辦公室、工研院與台灣 SoC 聯盟將以此為出發點,近期將規劃召開相關產學研合作整合運作會議,期能早日推動台灣 SoC 產業打響名號於國際舞台。

■ 附給

- 加方廠商出席名錄

* by alphabet

Company	Description	Website
ATI Technologies,	Products: Gamer, Multimedia, Mobile, Workstation,	http://www.ati.com/
Toronto	Handheld, Integrated, Digital TV, Embedded, Mac,	
Dr. Ramesh	Software	
Senthinathan, Director,		
Canadian	The Canadian Microelectronics Corporation	http://www.cmc.ca/
Microelectronics	The CMC-university-industry-government partnership	-
Corporation(CMC)	helps to produce individuals with the finest knowledge and	
Dr. Brian Burge,	skills in microelectronics, related areas of photonics,	
President and CEO	optoelectronics and micromachining, and progressively in	
Mr. Peter A. Stokes,	nano-scale technologies.	

company focused of Defined Radio (SD Processing (DSP) I density processing programmability an fast-paced, ever-ch Founded with more development at Sir Laboratory, Cogent extremely small an Diablo Technologies, Ottawa Diablo Technologies, Ottawa Mr. Riccardo Badalone, CTO Image Power Image Power Image Power Image Power deve compression techn for use in a range of use to implementat ASICs (Application FPGAs (Field Prog Products: Desktop Products: Desktop Products, ASIC/FPGA Products) Nosys Sreedhar Natarajan, Director Dr. Ashraf Salem Mosys Sreedhar Natarajan, Director Dr. Ashraf Salem Founded in 1991, N innovative memory single transistor bit results in the techn than traditional four the same standard 1T-SRAM technolog interface and high paccess cycles associadition, this techn consumption by a form of SRAM technology, technology for emboration both in search single production both in search single sin MoSys's headquartered at 1 California 94085.	nc. is a fabless semiconductor	
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	loSys develops, licenses and mark technology for semiconductors. The cell used in 1T-SRAM technology plogy achieving much higher density or six transistor SRAMs while using ogic manufacturing processes. By also offers the familiar, refresh-freerformance for random address ciated with traditional SRAMs. In plogy can reduce operating power actor of four compared with tradition contributing to making it an ideal edding large memories in System of a 1T-SRAM technology is in volume and alone memories. MoSys is 200 Stewart Drive, Sunnyvale,	e m/ y g nee nal on e as
	communications, using the right ensure the protection of your wirele	http://www.ne2encrypt ion.com
Jose Dr. Andrzej Strojwas, CTO of Process-Design circuits (ICs). PDF's enable semiconduct manufacturable IC manufacturing process.	(Nasdaq: PDFS) is a leading provintegration technologies for integrat	ted ices
in Europe and Japa	software, methodologies and servitor companies to create more designs and more capable esses. Headquartered in San Jose, rates worldwide with additional officin.	

	一 500 四床又返自贼人多的打任 田四根日	1
Pultronica Montreal	range of MIPS-based™ processors, high speed mixed signal and communication semiconductors. These products are used in enterprise, access, metro transport, wireless, and storage area network equipment. The company's MIPS-based processors are also designed into printers and other advanced consumer electronic applications. Product Families: MIPS-basedTM Processors, Advanced Clock Management, Storage Devices, SERDES Devices, Networking Devices, Wireless BSC/BTS	com/
Pultronics, Montreal	Develop high-frequency switch matrices.	http://www.pultronics.
Dr. Bozena Kaminska,	Telecommunications, Automotive Engineering, Low Power	<u>com</u>
CEO	Design	
Scanimetrics Steve Slupsky - CEO	Scanimetrics was incorporated in Alberta, Canada on January 10, 2001 with the mission to develop and sell micron-scale wireless telemetry technology that enables the wireless, non-contact testing of semiconductors. Scanimetrics is supported in part by the Alberta Ingenuity Fund, the National Research Council of Canada Industrial Research Assistance Program (IRAP), and Western Economic Diversification.	http://www.scanimetrics.com
SilicoMotive Inc. Jerzy Swic, President	Silicomotive Solutions Inc. is a privately held and funded integrated circuit design services firm, specializing in providing cutting edge System-on-Chip expertise to the global semiconductor industry. Our result oriented team of experienced IC design, verification as well as software engineers has a valuable record of achievements in helping organizations achieve	http://www.silicomotiv e.com/index.shtml
SiWorks, Calgary Mr. Mike Lee, Director,	competitive advantages by focusing on time-to-market effectiveness and design quality. A wireless semiconductor intellectual property company. Wireless Lan IP, Digital signal processing IP, Encryption/Decryption IP, Analog/Mixed-signal IP	http://www.siworks.co m
Smart Camera Technologies Inc	Researcher developed a low-cost tracking technology using live-cameras and infra-red sensors. New technique to track and code moving objects that features lower complexity, higher accuracy and lesser bit representation. Smart Camera Technologies Inc. (a Calgary-based company incorporated in March 2003) is a spin-off form the University of Calgary. The new startup will commercialize applications that use camera systems to identify video objects based on their relative apparent speed. The company has been Incorporate as of March 26,2003 and it is currently mentored by the InnoCentre Alberta	
Snowbush Microelectronics, Toronto Dr. Ken Martin, President and Co-Founder,	A supplier of analog and mixed signal intellectual and design servies. Data Converters, Reference Circuits, Clock & Data Recovery, Filters, Communications AFE, Drivers & Amplifiers	http://www.snowbush. com
TRLabs in Calgary	A not-for-profit information and communications technology research consortium Products: Wireless Communications, Data Networking, Network Access, Photonics, Network Systems, Research Tools	http://www.trlabs.ca/

- 照片選輯



7/18 相見歡 左起:馬金溝、林寶樹、楊丁元、黃威、溫瓌岸 (敬稱略)



7/19 旺玖科技張榮輝總工程師present "Media Streaming SoC Development and Application"



7/19 Short Presentation and Discussion 中間兩位為交大李鎮宜主任與溫 岸教授



7/20 源捷楊丁元董事長與加方廠商NE2的一對一對談



7/20 商談會後的大合照



7/20 會議結束後的慶功宴



所有產業界的參加者:

左起聯電莫亞楠副部長,旺玖科技張榮輝總工程師,台積電張彌彰處長,智原黃克勤經理,台灣 SoC聯盟主席及源捷董事長楊丁元博士,台灣SoC聯盟/工研院系統晶片中心謝秀卿經理



7/22 拜訪TRLabs



7/23 拜訪PMC-Sierra



happy trip!